

## Amendments to the Specification

Please replace the paragraph on page 23, lines 1-28, with the following amended paragraph:

Fig. 9 shows a further embodiment of a magnet assembly at the target resulting in an asymmetrically unbalanced magnet field pattern. This assembly has a first looping magnet subarrangement  $87_o$  of one polarity and having a radius-like extension  $87_{o1}$ . The second magnet subarrangement  $87_i$  is provided distant from and along the outer magnet subarrangement  $87_o$ .

These two magnet subarrangements do generate on one hand the magnetron field pattern  $F_M$  and the asymmetrically unbalanced field pattern with an area  $P$  of maximum flux as shown in fig. 9. The locus of zero field component of the magnetron field pattern  $F_M$  defines for the locus  $L'$  as was already shown in Figs. 1 and 2, thereby confining the outer area  $A_o$  with respect to the inner area  $A_i$ . Thereby, at the right-hand side of the arrangement of Fig. 9 the outer magnet subarrangement  $87_o$  projects ~~from~~ towards the respective edge of the target arrangement shown at 88. The projecting area  $A_A$  of magnet subarrangement  $87_o$  causes the asymmetry of the unbalanced magnetic field. Only at that area  $A_A$  the magnetron field pattern  $F_M$  does not emanate from the target surface which is limited at line 88. This area  $A_A$  is not more than 12% of the target surface area. When performing the method according to the present invention, i.e. operating the magnetron source and magnetron chamber, especially for sputter-coating the following further settings are preferred:

The plasma is preferably fed with a power in the range of 0.1 to 60 kW, thereby even more preferred within a range of 1 to 40 kW.